## AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 09/964,586 Filing Date: September 28, 2001

Title: PACKAGE STIFFENER (As Amended)

Assignee: Intel Corporation

## IN THE SPECIFICATION

Please amend the Specification at the paragraph beginning on page 11, line 17 as follows:

In addition, the PGID frame 610 may provide stiffening support when attached to a thin-core, or coreless substrate 110, acting as a PGID/IS. As one example embodiment of the present invention, a stiffener frame (edge, ring) providing stiffening support to a thin-core or coreless substrate may be constructed so as to serve a double function providing the power, ground or inductance to the substrate. Located on a major die side plane of the substrate, the PGID/IS frame may extend (e.g. inwardly) from the lip of the substrate 110 towards the center of the substrate. The PGID/IS may be formed of any PGID material providing a degree of stiffness or rigidity to the thin-core or coreless substrate.